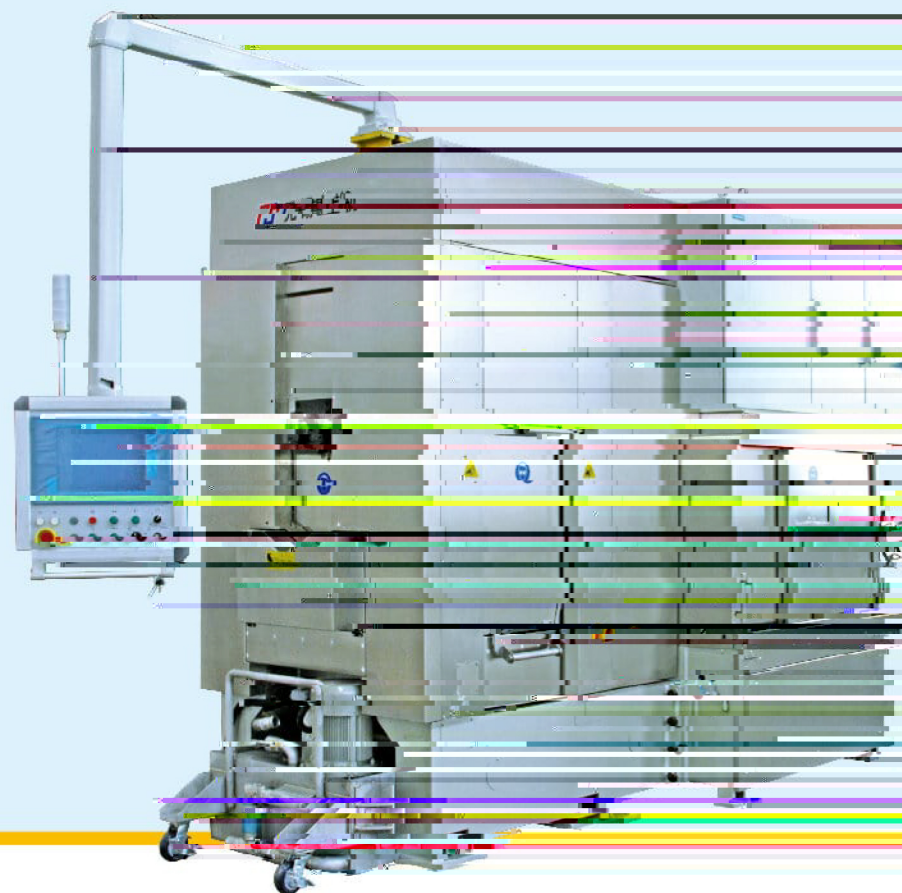


WSK060

蓝宝石切片机

WSK060 Sapphire Slicing Machine



设备用途/应用范围

- 本机床用于蓝宝石的切割、研磨、抛光等工序，也可用于切割硅、锗、石英玻璃、陶瓷、蓝宝石晶体等。
- 机床所有电器元件均采用国际知名品牌，保证机床的稳定性。
- 采用西门子组态技术的一体化PC机，15"触摸屏。
- 电控柜配备温度监控系统，保证安全。
- 设备具备缓进功能，可设置进给速度，防止由于进给速度过快导致的崩边、裂纹等缺陷，缩短了切割时间，并提高了晶片的品质。
- 滑轮数量最少化设计（仅6个滑轮），减少切割时的摩擦。

应用范围/适用范围

- This machine is used for processing sapphire, silicon, germanium, ceramics, sapphire crystals, etc.
- All electrical components adopt international famous brands to ensure the stability of the machine.
- Apply integrated PC of SIEMENS SIMATIC controlling system, 15" touch screen.
- The electric control cabinet is equipped with temperature monitoring system to ensure the safety.
- The equipment has a slow feed function, which can set the feed speed to avoid the defects such as chipping, cracking, etc. caused by too fast feed speed, shorten the cutting time, and improve the quality of the wafer.
- Minimal design with less rollers (only 6 rollers), reduce the friction during cutting.

主要参数/主要技术参数

长度/Length	4600mm
厚度/Thickness	>0.2mm

主要参数/主要技术参数

导轮直径/Guide wheel diameter	220mm
导轮轴距/Center wheel base	440mm
导轮长度/Guide wheel length	630mm
切割速度/Cutting speed	0.01mm~0.05mm/min
摆动角度/Swinging angle	±12°
切割方向/Cutting direction	forward or reverse cutting/双向切割
存储线圈/Storage coil	200m
冷却水/Chilling water	220L/min

主要参数/主要技术参数

电动机功率/Motor power	220/380V, 30HP, 1500r/min
冷却水流量/Cooling water flow	20L/min
冷却水压/Cooling water pressure	12~15kg/cm²

外形尺寸/外形尺寸

机床外形尺寸(长×宽×高)/equipment size (L×W×H)	4600×2400×2100mm
机床重量/weight	12000kg

示意图/示意图

